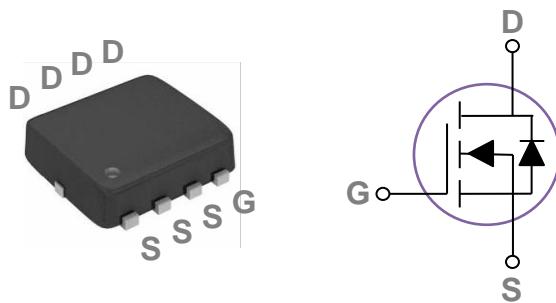


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK3X3 Pin Configuration



BVDSS	RDS(ON)	ID
60V	15mΩ	35A

### Features

- 60V,35A,  $RDS(ON) = 15m\Omega$  @ $VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting
- Quick Charger

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	35	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	22	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	140	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	45	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	30	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	46	W
	Power Dissipation – Derate above 25°C	0.37	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.7	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

**On Characteristics**

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=10\text{A}$	---	13	15	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=5\text{A}$	---	16	19	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1.2	1.7	2.5	V
$\text{gfs}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=3\text{A}$	---	10	---	S

**Dynamic and switching Characteristics**

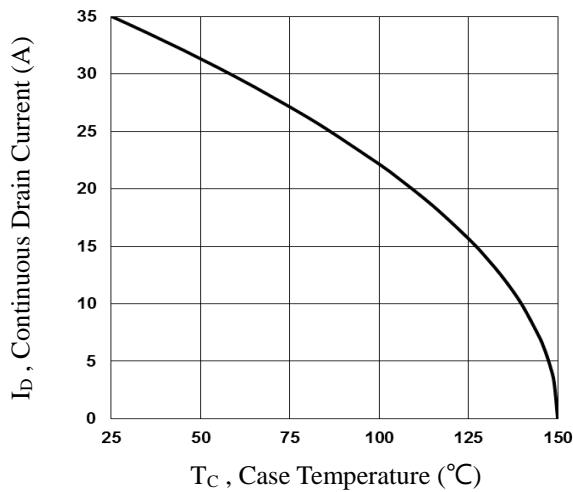
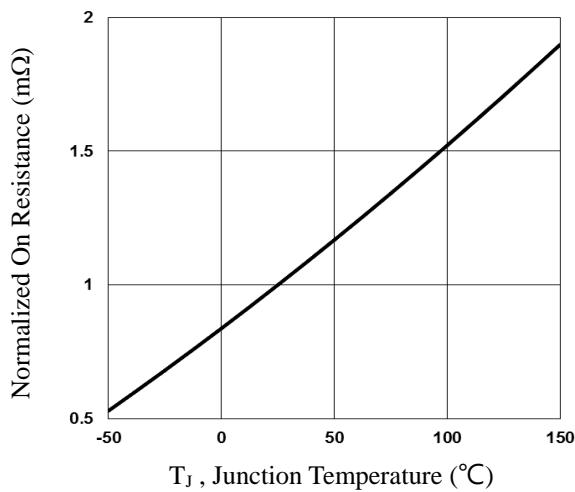
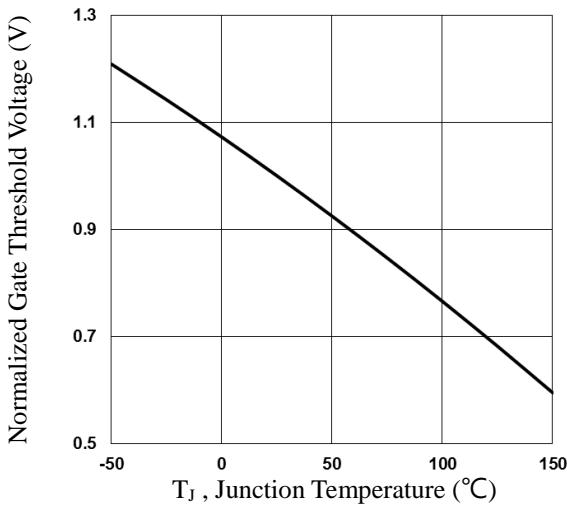
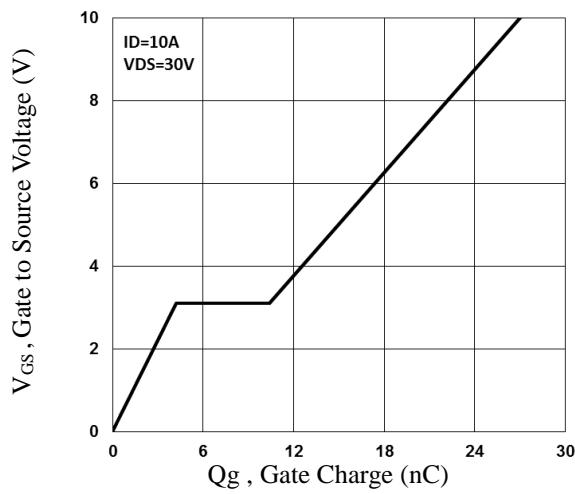
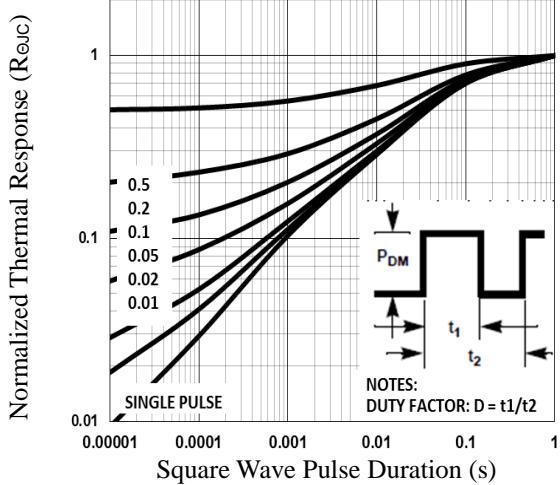
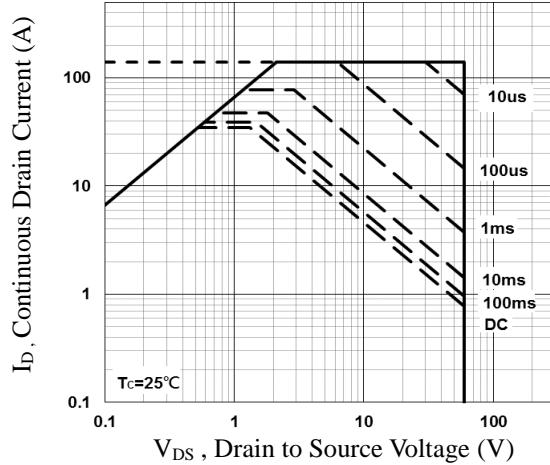
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=10\text{A}$	---	27	54	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	4.2	9	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	6.2	12	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$ $I_D=1\text{A}$	---	8.6	16	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	24.2	48	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	32.3	64	
$T_f$	Fall Time <sup>3, 4</sup>		---	7.9	16	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	1515	3000	pF
$C_{\text{oss}}$	Output Capacitance		---	120	200	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	76	120	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.8	3.6	$\Omega$

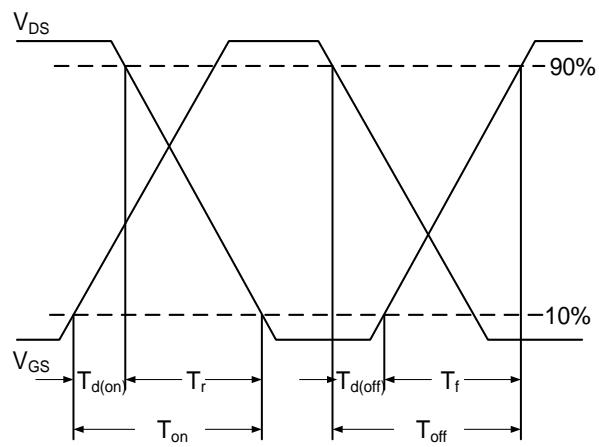
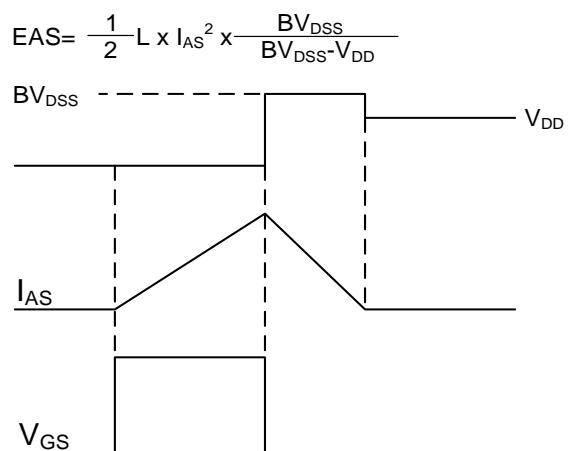
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	35	A
			---	---	70	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
			---	19	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $di/dt=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	---	5	---	nC

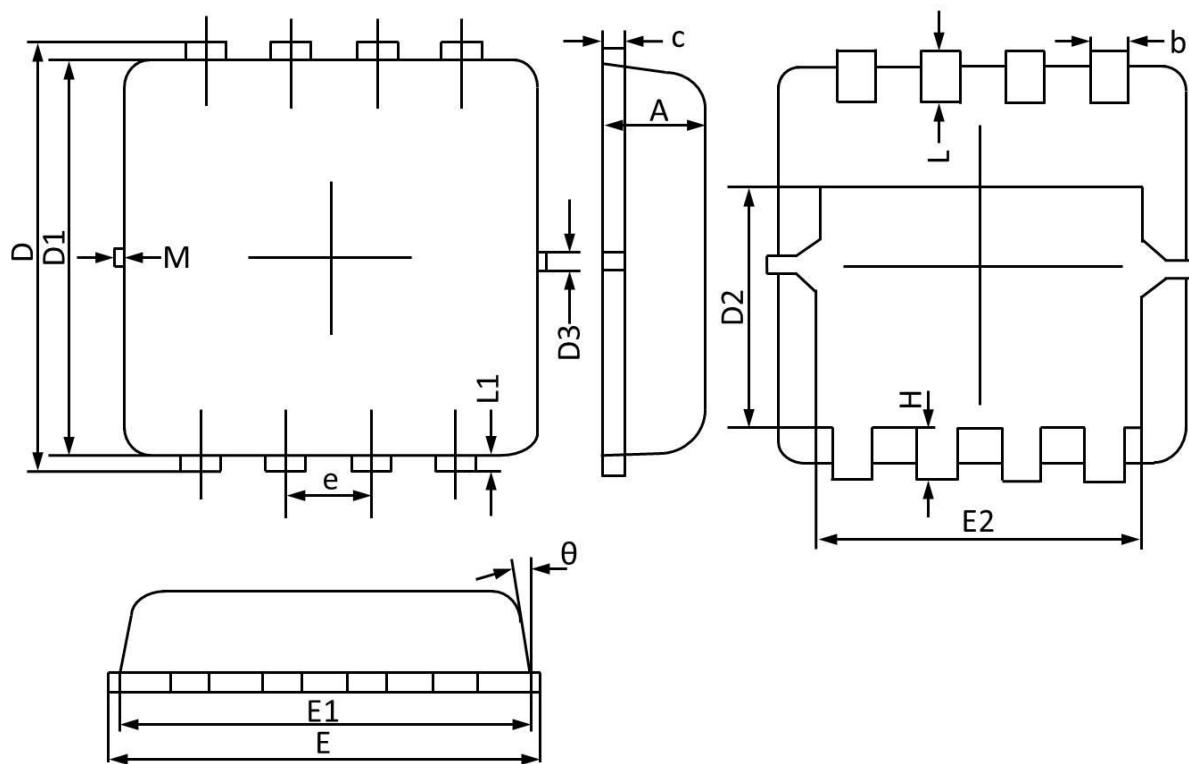
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=30\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**

**Fig.2 Normalized R<sub>DS(on)</sub> vs. T<sub>j</sub>**

**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 EAS Waveform**

## PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	<b>0.700</b>	<b>0.800</b>	<b>0.028</b>	<b>0.031</b>
b	<b>0.250</b>	<b>0.350</b>	<b>0.010</b>	<b>0.013</b>
c	<b>0.100</b>	<b>0.250</b>	<b>0.004</b>	<b>0.009</b>
D	<b>3.250</b>	<b>3.450</b>	<b>0.128</b>	<b>0.135</b>
D1	<b>3.000</b>	<b>3.200</b>	<b>0.119</b>	<b>0.125</b>
D2	<b>1.780</b>	<b>1.980</b>	<b>0.070</b>	<b>0.077</b>
D3	<b>0.130 REF</b>		<b>0.005 REF</b>	
E	<b>3.200</b>	<b>3.400</b>	<b>0.126</b>	<b>0.133</b>
E1	<b>3.000</b>	<b>3.200</b>	<b>0.119</b>	<b>0.125</b>
E2	<b>2.390</b>	<b>2.590</b>	<b>0.094</b>	<b>0.102</b>
e	<b>0.650 BSC</b>		<b>0.026 BSC</b>	
H	<b>0.300</b>	<b>0.500</b>	<b>0.011</b>	<b>0.019</b>
L	<b>0.300</b>	<b>0.500</b>	<b>0.011</b>	<b>0.019</b>
L1	<b>0.130 REF</b>		<b>0.005 REF</b>	
θ	<b>0°</b>	<b>12°</b>	<b>0°</b>	<b>12°</b>
M	<b>0.150 REF</b>		<b>0.006 REF</b>	